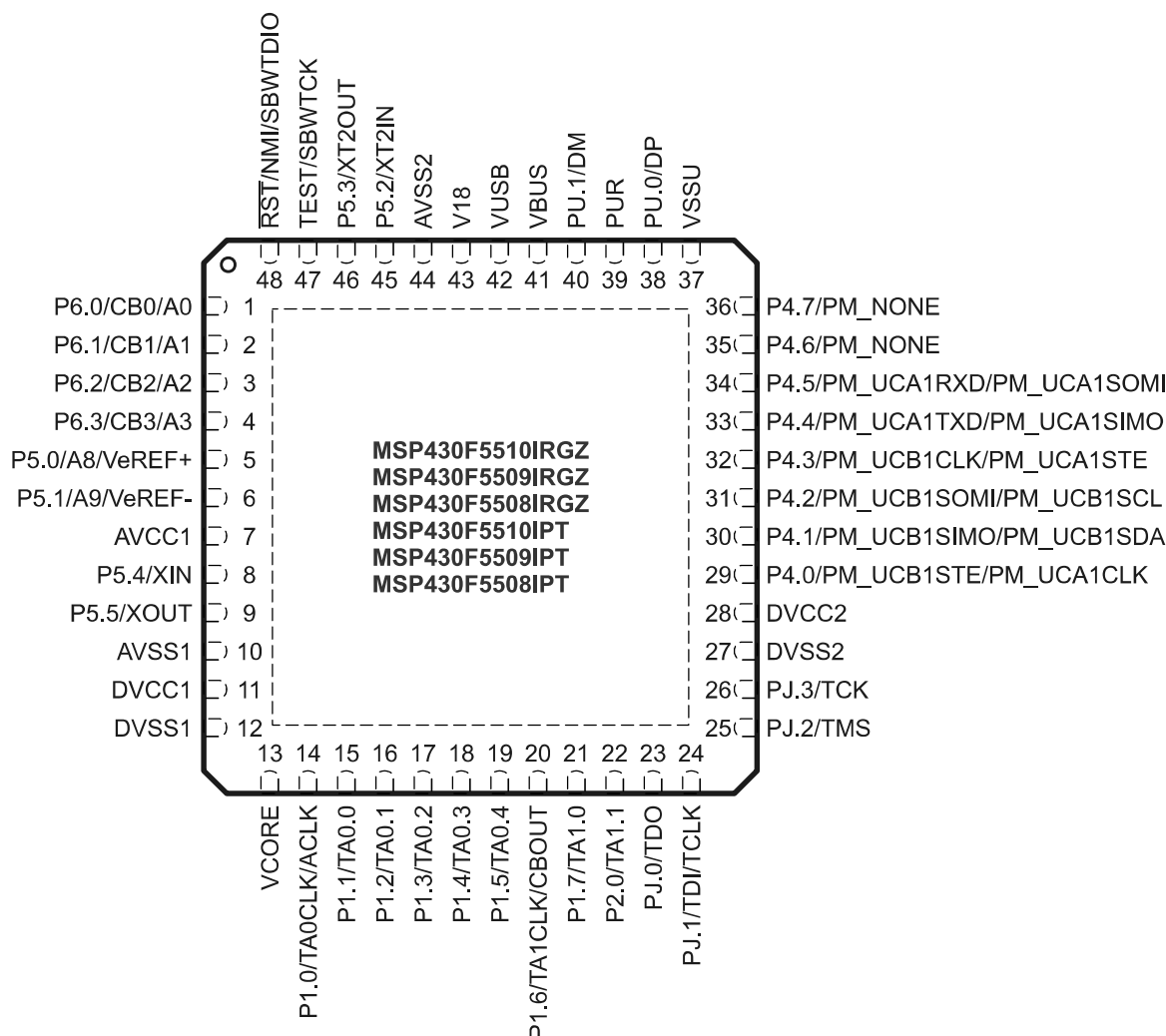


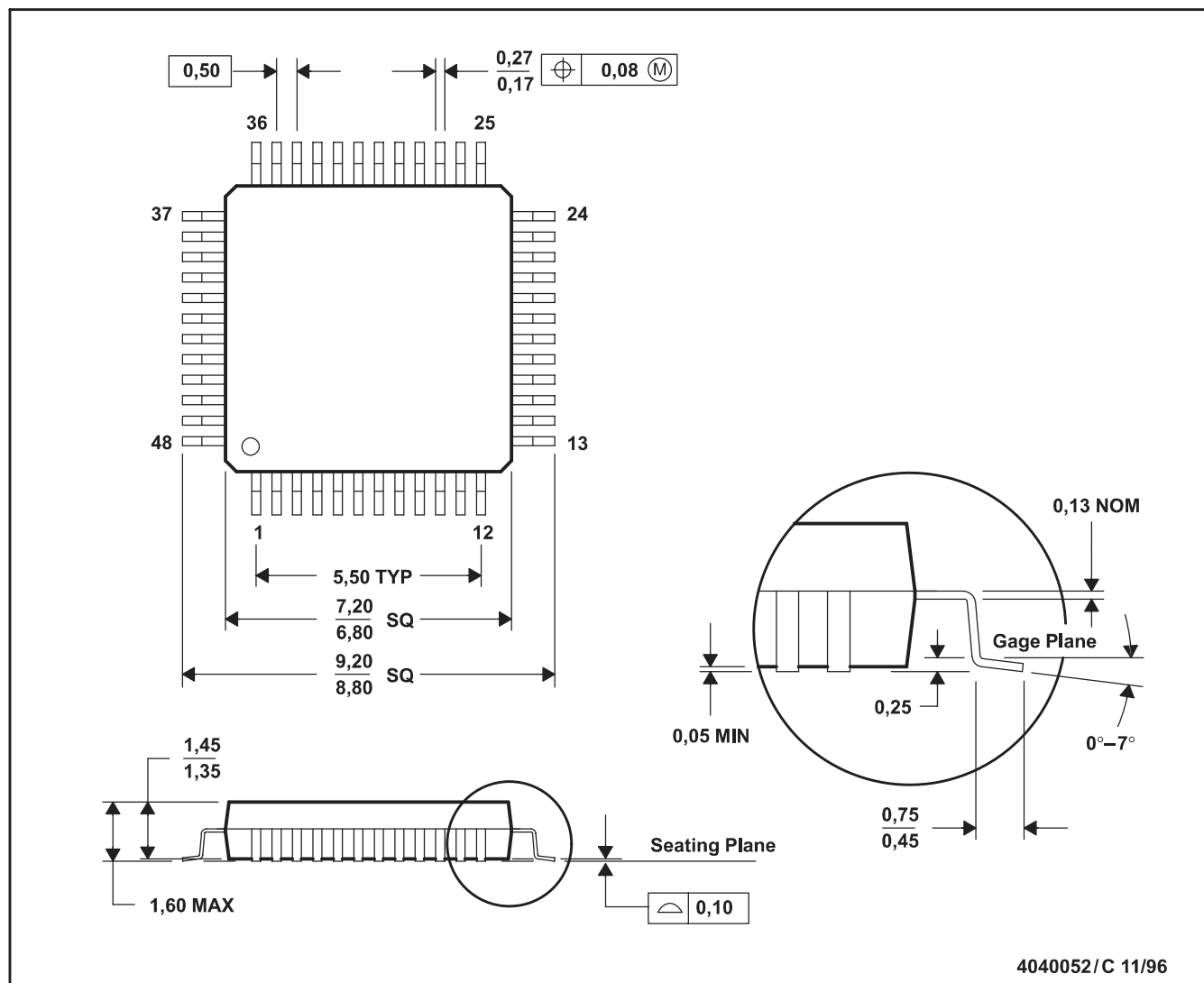
**Pin Designation – MSP430F5510IRGZ, MSP430F5509IRGZ, MSP430F5508IRGZ,
MSP430F5510IPT, MSP430F5509IPT, MSP430F5508IPT**



NOTE: TI recommends connection of the exposed thermal pad to V_{SS}.

PT (S-PQFP-G48)

PLASTIC QUAD FLATPACK



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Falls within JEDEC MS-026
 - This may also be a thermally enhanced plastic package with leads connected to the die pads.